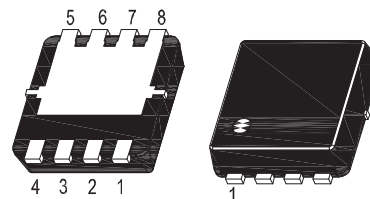
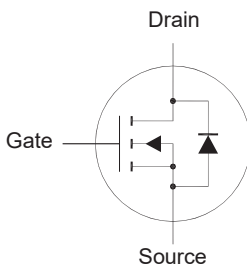


## N-Channel Enhancement Mode MOSFET

### Features

- Surface-mounted package
- Low Gate-Source Threshold Voltage
- Halogen and Antimony Free(HAF)  
RoHS compliant



1. Source 2. Source 3. Source 4. Gate  
5. Drain 6. Drain 7. Drain 8. Drain  
DFN3030 Plastic Package

### Key Parameters

| Parameter        | Value                  | Unit       |
|------------------|------------------------|------------|
| $BV_{DSS}$       | 40                     | V          |
| $R_{DS(ON)}$ Max | 5.7 @ $V_{GS} = 10$ V  | m $\Omega$ |
|                  | 7 @ $V_{GS} = 4.5$ V   |            |
| $V_{GS(th)}$ typ | 1.6                    | V          |
| $Q_g$ typ        | 69.9 @ $V_{GS} = 10$ V | nC         |

### Absolute Maximum Ratings (at $T_a = 25^\circ\text{C}$ unless otherwise specified)

| Parameter                                        | Symbol                    | Value         | Unit             |
|--------------------------------------------------|---------------------------|---------------|------------------|
| Drain-Source Voltage                             | $V_{DS}$                  | 40            | V                |
| Gate-Source Voltage                              | $V_{GS}$                  | $\pm 20$      | V                |
| Drain Current - Continuous                       | $I_D$                     | 52            | A                |
|                                                  |                           | 32            |                  |
|                                                  | $T_c = 25^\circ\text{C}$  |               |                  |
|                                                  | $T_c = 100^\circ\text{C}$ |               |                  |
| Drain Current Pulsed <sup>1)</sup>               | $I_{DM}$                  | 220           | A                |
| Avalanche Current                                | $I_{AS}$                  | 20.3          | A                |
| Single Pulse Avalanche Energy <sup>2)</sup>      | $E_{AS}$                  | 103           | mJ               |
| Power Dissipation                                | $P_D$                     | 30            | W                |
|                                                  |                           |               |                  |
|                                                  | $T_c = 25^\circ\text{C}$  |               |                  |
| Operating Junction and Storage Temperature Range | $T_j, T_{stg}$            | - 55 to + 175 | $^\circ\text{C}$ |

### Thermal Characteristics

| Parameter                                                 | Symbol          | Max. | Unit               |
|-----------------------------------------------------------|-----------------|------|--------------------|
| Thermal Resistance from Junction to Case                  | $R_{\theta JC}$ | 5    | $^\circ\text{C/W}$ |
| Thermal Resistance from Junction to Ambient <sup>3)</sup> | $R_{\theta JA}$ | 58   | $^\circ\text{C/W}$ |

<sup>1)</sup> Pulse Test: Pulse Width  $\leq 100$   $\mu\text{s}$ , Duty Cycle  $\leq 2\%$ , Repetitive rating, pulse width limited by junction temperature  $T_{J(MAX)} = 175^\circ\text{C}$ .

<sup>2)</sup> Limited by  $T_{J(MAX)}$ , starting  $T_J = 25^\circ\text{C}$ ,  $L = 0.5$  mH,  $R_g = 25$   $\Omega$ ,  $I_{AS} = 20.3$  A,  $V_{GS} = 10$  V.

<sup>3)</sup> Device Surface Mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate, in a still air.

Characteristics at  $T_a = 25^\circ\text{C}$  unless otherwise specified

| Parameter                                                                                                                                                                        | Symbol       | Min.   | Typ.       | Max.      | Unit          |
|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------|--------|------------|-----------|---------------|
| <b>STATIC PARAMETERS</b>                                                                                                                                                         |              |        |            |           |               |
| Drain-Source Breakdown Voltage<br>at $I_D = 250\ \mu\text{A}$                                                                                                                    | $BV_{DSS}$   | 40     | -          | -         | V             |
| Drain-Source Leakage Current<br>at $V_{DS} = 32\ \text{V}$                                                                                                                       | $I_{DSS}$    | -      | -          | 1         | $\mu\text{A}$ |
| Gate-Source Leakage Current<br>at $V_{GS} = \pm 20\ \text{V}$                                                                                                                    | $I_{GSS}$    | -      | -          | $\pm 100$ | nA            |
| Gate-Source Threshold Voltage<br>at $V_{DS} = V_{GS}$ , $I_D = 250\ \mu\text{A}$                                                                                                 | $V_{GS(th)}$ | 1      | -          | 2.5       | V             |
| Drain-Source On-State Resistance<br>at $V_{GS} = 10\ \text{V}$ , $I_D = 10\ \text{A}$<br>at $V_{GS} = 4.5\ \text{V}$ , $I_D = 5\ \text{A}$                                       | $R_{DS(on)}$ | -<br>- | 4.6<br>-   | 5.7<br>7  | m $\Omega$    |
| <b>DYNAMIC PARAMETERS</b>                                                                                                                                                        |              |        |            |           |               |
| Forward Transconductance<br>at $V_{DS} = 5\ \text{V}$ , $I_D = 5\ \text{A}$                                                                                                      | $g_{fs}$     | -      | 18.8       | -         | S             |
| Gate resistance<br>at $V_{GS} = 0\ \text{V}$ , $V_{DS} = 0\ \text{V}$ , $f = 1\ \text{MHz}$                                                                                      | $R_g$        | -      | 0.5        | -         | $\Omega$      |
| Input Capacitance<br>at $V_{GS} = 0\ \text{V}$ , $V_{DS} = 20\ \text{V}$ , $f = 1\ \text{MHz}$                                                                                   | $C_{iss}$    | -      | 3255       | -         | pF            |
| Output Capacitance<br>at $V_{GS} = 0\ \text{V}$ , $V_{DS} = 20\ \text{V}$ , $f = 1\ \text{MHz}$                                                                                  | $C_{oss}$    | -      | 260        | -         | pF            |
| Reverse Transfer Capacitance<br>at $V_{GS} = 0\ \text{V}$ , $V_{DS} = 20\ \text{V}$ , $f = 1\ \text{MHz}$                                                                        | $C_{rss}$    | -      | 195        | -         | pF            |
| Gate charge total<br>at $V_{DS} = 20\ \text{V}$ , $I_D = 10\ \text{A}$ , $V_{GS} = 10\ \text{V}$<br>at $V_{DS} = 20\ \text{V}$ , $I_D = 10\ \text{A}$ , $V_{GS} = 4.5\ \text{V}$ | $Q_g$        | -<br>- | 69.9<br>33 | -<br>-    | nC            |
| Gate to Source Charge<br>at $V_{DS} = 20\ \text{V}$ , $I_D = 10\ \text{A}$ , $V_{GS} = 10\ \text{V}$                                                                             | $Q_{gs}$     | -      | 10         | -         | nC            |
| Gate to Drain Charge<br>at $V_{DS} = 20\ \text{V}$ , $I_D = 10\ \text{A}$ , $V_{GS} = 10\ \text{V}$                                                                              | $Q_{gd}$     | -      | 13         | -         | nC            |
| Turn-On Delay Time<br>at $V_{DS} = 20\ \text{V}$ , $I_D = 10\ \text{A}$ , $V_{GS} = 10\ \text{V}$ , $R_g = 3.3\ \Omega$                                                          | $t_{d(on)}$  | -      | 22         | -         | ns            |
| Turn-On Rise Time<br>at $V_{DS} = 20\ \text{V}$ , $I_D = 10\ \text{A}$ , $V_{GS} = 10\ \text{V}$ , $R_g = 3.3\ \Omega$                                                           | $t_r$        | -      | 26         | -         | ns            |
| Turn-Off Delay Time<br>at $V_{DS} = 20\ \text{V}$ , $I_D = 10\ \text{A}$ , $V_{GS} = 10\ \text{V}$ , $R_g = 3.3\ \Omega$                                                         | $t_{d(off)}$ | -      | 21         | -         | ns            |
| Turn-Off Fall Time<br>at $V_{DS} = 20\ \text{V}$ , $I_D = 10\ \text{A}$ , $V_{GS} = 10\ \text{V}$ , $R_g = 3.3\ \Omega$                                                          | $t_f$        | -      | 3          | -         | ns            |
| <b>Body-Diode PARAMETERS</b>                                                                                                                                                     |              |        |            |           |               |
| Drain-Source Diode Forward Voltage<br>at $I_S = 1\ \text{A}$ , $V_{GS} = 0\ \text{V}$                                                                                            | $V_{SD}$     | -      | -          | 1.2       | V             |
| Body-Diode Continuous Current                                                                                                                                                    | $I_S$        | -      | -          | 52        | A             |
| Body-Diode Continuous Current, Pulsed                                                                                                                                            | $I_{SM}$     | -      | -          | 220       | A             |
| Body Diode Reverse Recovery Time<br>at $I_S = 10\ \text{A}$ , $di/dt = 100\ \text{A}/\mu\text{s}$                                                                                | $t_{rr}$     | -      | 16         | -         | ns            |
| Body Diode Reverse Recovery Charge<br>at $I_S = 10\ \text{A}$ , $di/dt = 100\ \text{A}/\mu\text{s}$                                                                              | $Q_{rr}$     | -      | 9          | -         | nC            |

Fig. 1 Typical Output Characteristics

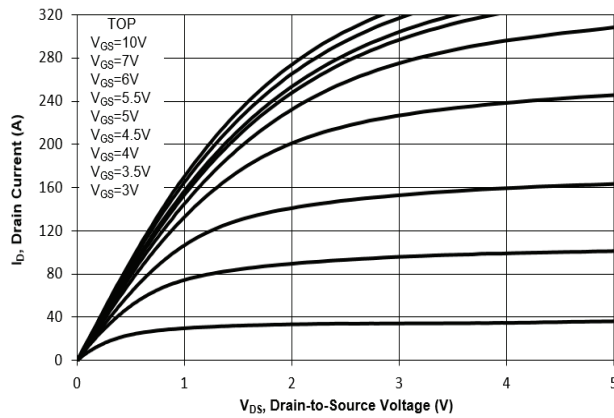


Fig. 2 Typical Transfer Characteristics

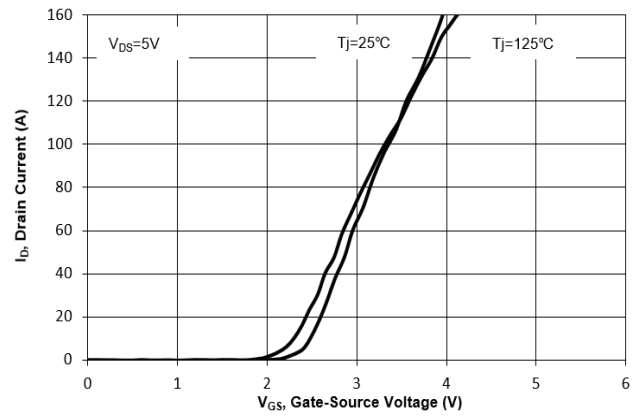


Fig. 3 On-Resistance vs. Drain Current

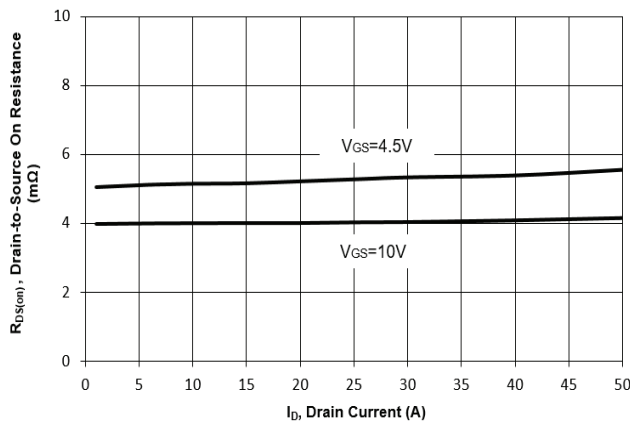


Fig. 4 On-Resistance vs. Gate to Source Voltage

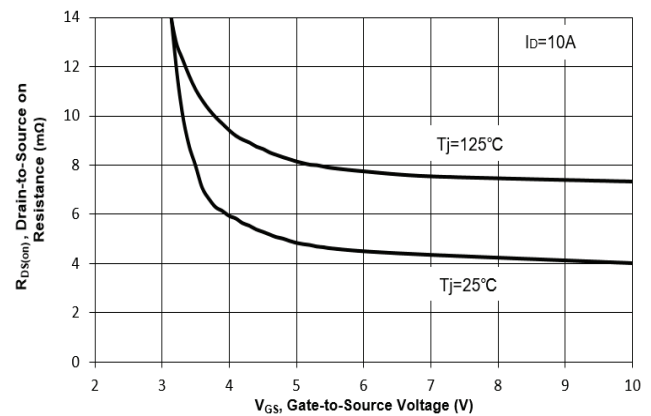


Fig. 5 On-Resistance vs.  $T_J$

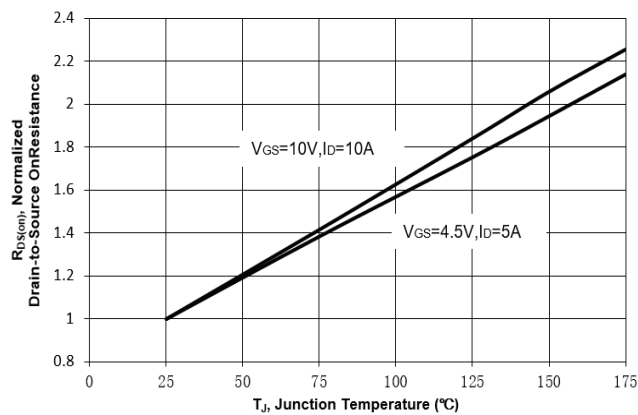
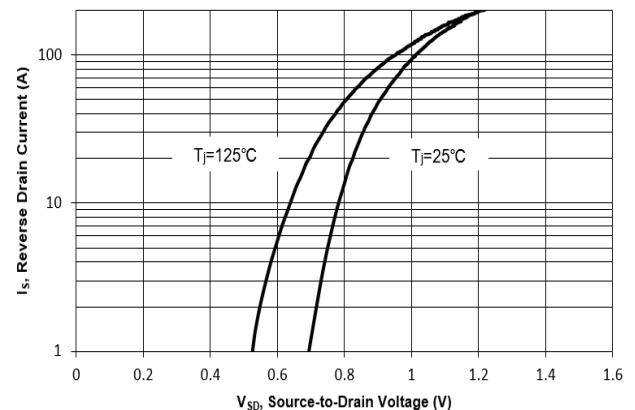


Fig. 6 Typical Body-Diode Forward Characteristics



## Electrical Characteristics Curves

Fig. 7 Typical Junction Capacitance

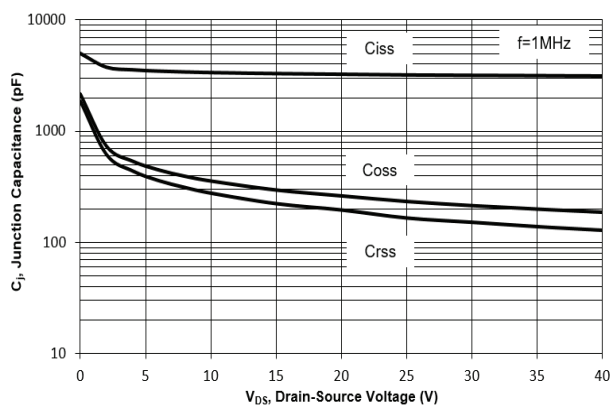


Fig. 8 Drain-Source Leakage Current vs.  $T_J$

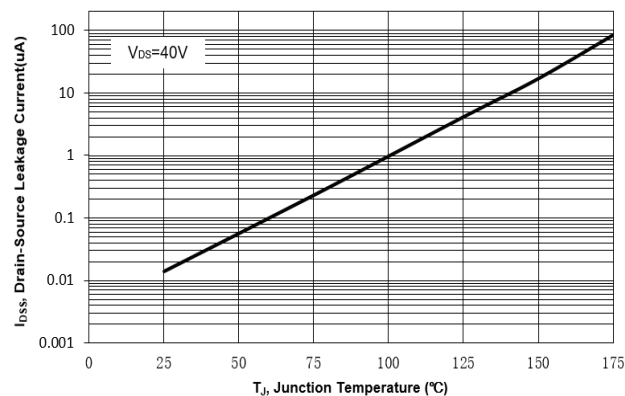


Fig. 9  $V_{(BR)DSS}$  vs. Junction Temperature

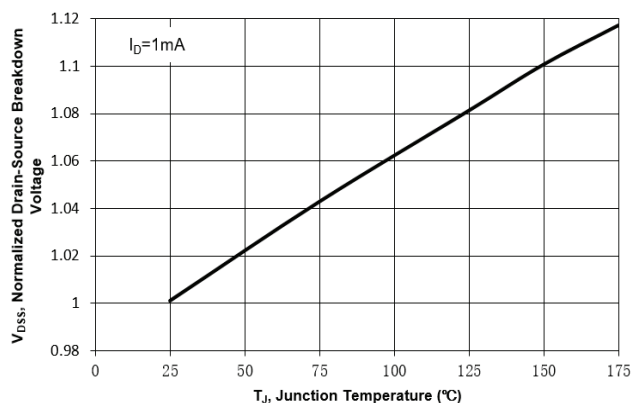


Fig. 10 Gate Threshold Variation vs.  $T_J$

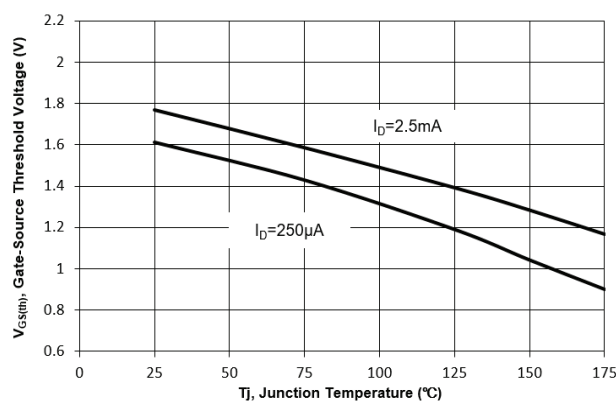


Fig. 11 Gate Charge

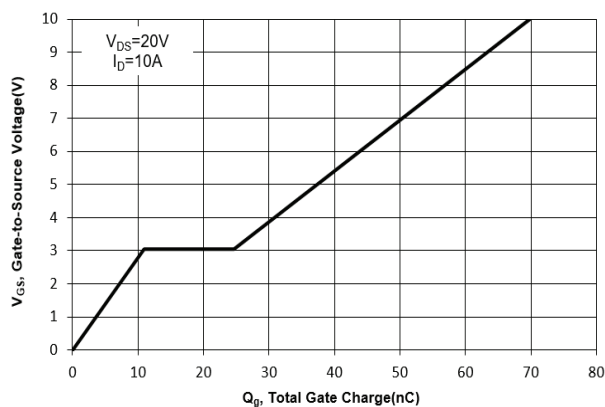
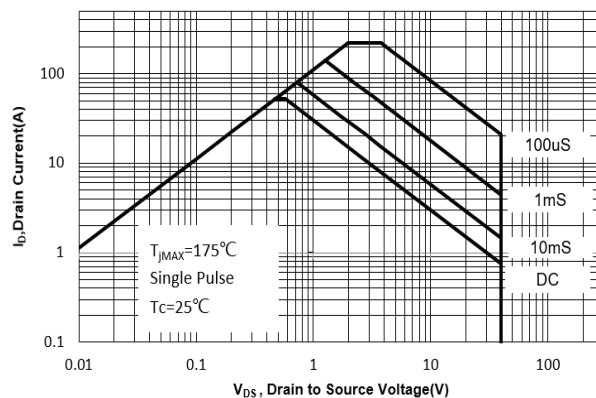


Fig. 12 Safe Operation Area



## Electrical Characteristics Curves

Fig.13 Normalized Maximum Transient Thermal Impedance( $Z_{\theta JC}$ )

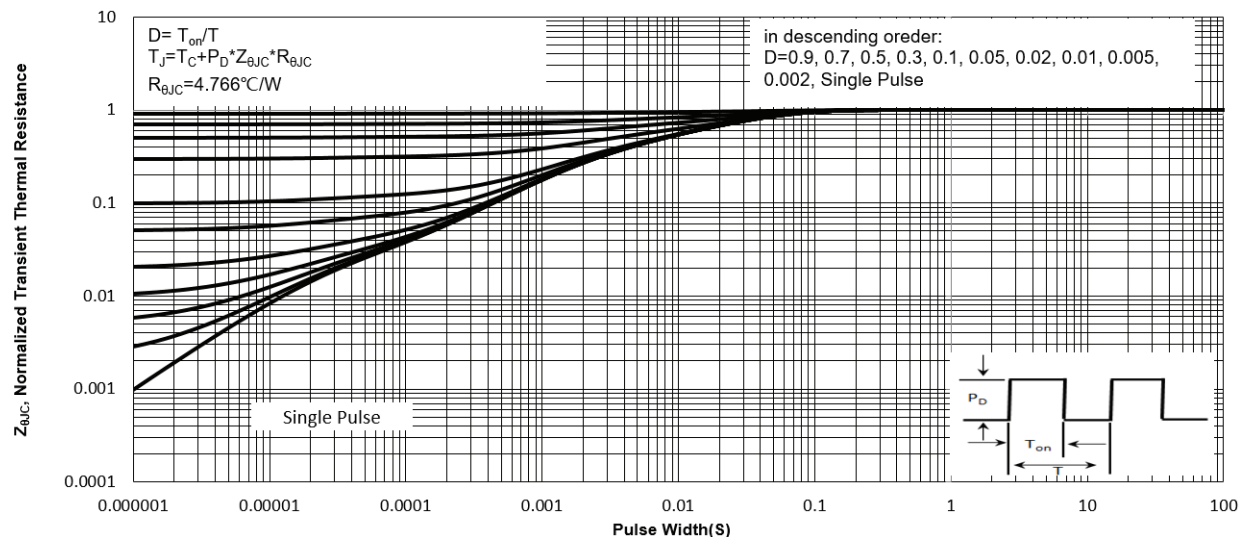
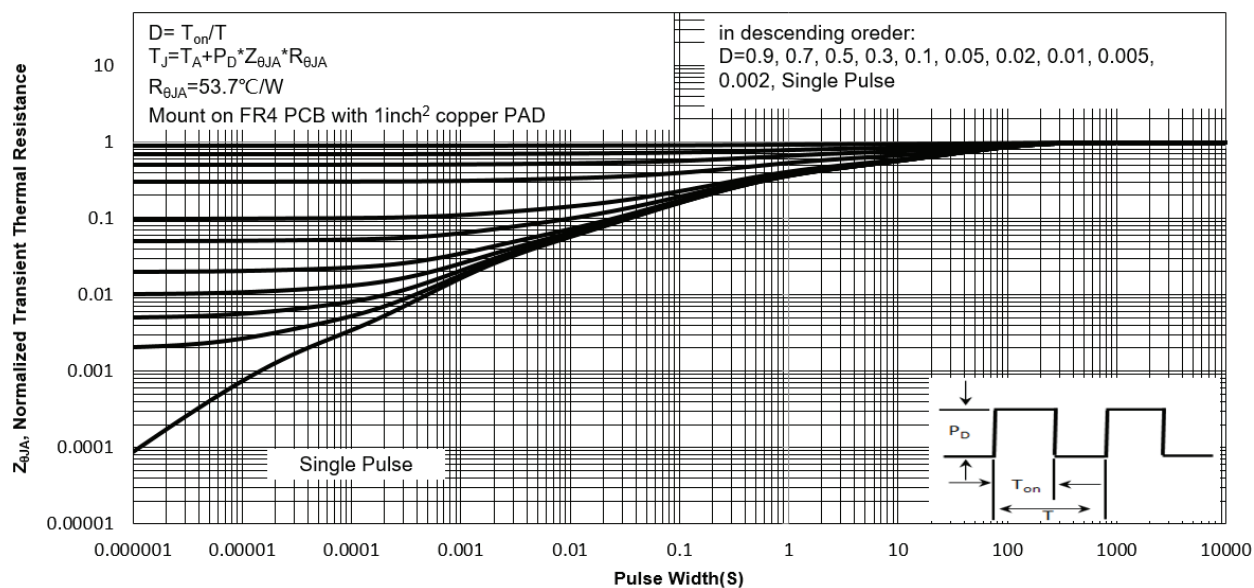


Fig.14 Normalized Maximum Transient Thermal Impedance( $Z_{\theta JA}$ )



## Test Circuits

Fig.1-1 Switching times test circuit

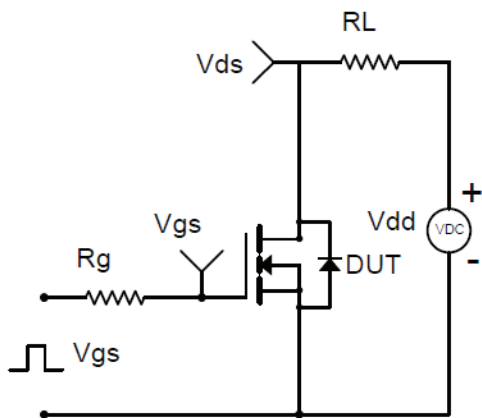


Fig.1-2 Switching Waveform

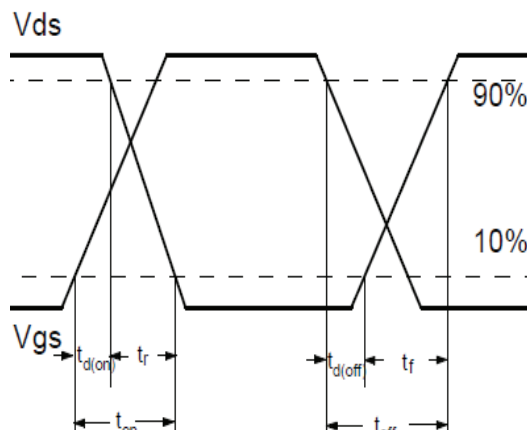


Fig.2-1 Gate charge test circuit

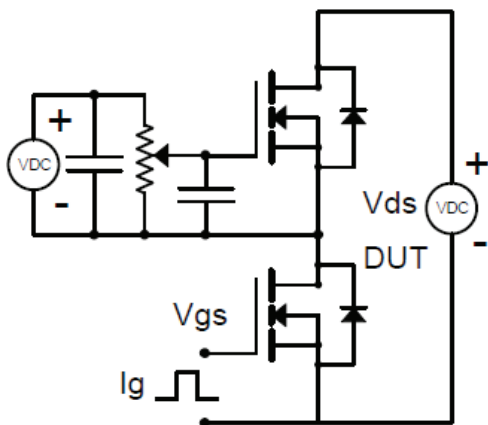


Fig.2-2 Gate charge waveform

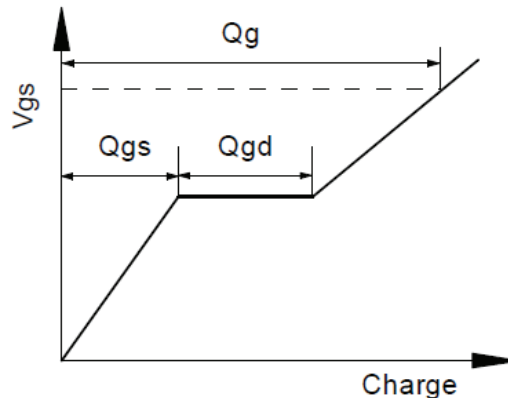


Fig.3-1 Avalanche test circuit

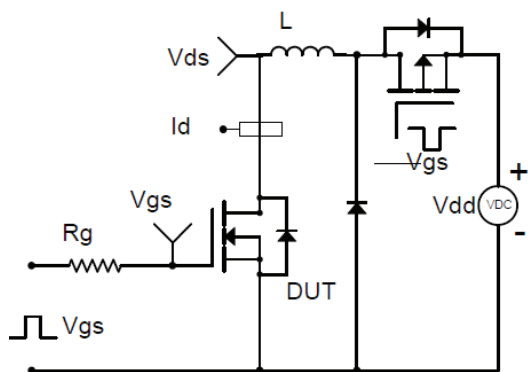


Fig.3-2 Avalanche waveform

